IN THE CLAIMS:

Please cancel claims 10-27, add new claims 28-36, and amend the claims as follows:

1. (Currently Amended) An electrochemical plating apparatus, comprising:

a plating cell configured to contain a plating bath;

a substrate support member positioned ~~above~~ in the plating cell ~~bath~~ and ~~being~~ configured to selectively contact the plating bath with a substrate secured thereto;

~~an electrolyte~~ a fluid supply line in fluid communication with the plating cell ~~bath~~;

a selectively actuated check valve positioned in the ~~electrolyte~~ fluid supply line; and

~~an electrolyte~~ a bleed line in fluid communication with the plating cell ~~bath~~.

2. (Currently Amended) The electrochemical plating apparatus of claim 1, wherein the ~~electrolyte~~ bleed line in positioned in a side wall of the plating cell ~~bath~~ and is configured to drain a portion of ~~electrolyte from~~ the plating bath.

3. (Currently Amended) The electrochemical plating apparatus of claim 2, wherein the ~~electrolyte~~ bleed line is positioned in the side wall proximate a top portion of an anode ~~member~~ positioned in the plating cell ~~bath~~.

4. (Currently Amended) The electrochemical plating apparatus of claim 3, wherein the ~~electrolyte~~ bleed line is configured to drain ~~a portion of electrolyte from~~ the plating cell ~~bath~~, while leaving a sufficient amount of electrolyte in the plating cell ~~bath~~ to immerse the anode ~~member~~.

5. (Currently Amended) The electrochemical plating apparatus of claim 1, wherein the ~~electrolyte~~ bleed line further comprises a selectively actuated bleed valve.

6. (Currently Amended) The electrochemical plating apparatus of claim 1, further comprising a ~~microprocessor-type~~ microprocessor-type controller configured to regulate operational characteristics of the electrochemical plating apparatus.

7. (Currently Amended) The electrochemical plating apparatus of claim 6, wherein the ~~mirocroprocessor-type~~ microprocessor-type controller is configured to close the selectively actuated valve in the ~~electrolyte~~ fluid supply line and open the bleed line to drain a portion of the ~~plating bath from the~~ plating cell.

8. (Original) The electrochemical plating apparatus of claim 7, wherein the controller is configured to drain a portion of ~~the plating bath from~~ the plating cell during non-processing time periods by opening a selectively actuated bleed valve positioned in the bleed line.

9. (Currently Amended) The electrochemical plating apparatus of claim 3, wherein the ~~electrolyte~~ bleed line is configured to completely drain the ~~electrolyte from the~~ plating bath.

10-27. (Canceled)

28. (New) An electrochemical plating apparatus, comprising:

a plating cell configured to contain a plating bath;

a substrate support member positioned in the plating cell and configured to contact a substrate with the plating bath;

a fluid supply line in fluid communication with the plating cell;

an anode in the plating cell; and

a bleed line in fluid communication with the plating cell at a position in the plating cell above the anode.

29. (New) The electrochemical plating apparatus of claim 28, wherein the bleed line is configured to drain a portion of the plating bath from the plating cell, while leaving a sufficient amount of plating bath in the plating cell to immerse the anode.

30. (New) The electrochemical plating apparatus of claim 28, further comprising a check valve in the fluid supply line.

31. (New) The electrochemical plating apparatus of claim 30, wherein the check valve is selectively actuated.

32. (New) The electrochemical plating apparatus of claim 28, further comprising a valve in the bleed line.

33. (New) The electrochemical plating apparatus of claim 32, wherein the valve in the bleed line is selectively actuated.

34. (New) The electrochemical plating apparatus of claim 28, further comprising a microprocessor-type controller configured to regulate operational characteristics of the electrochemical plating apparatus.

35. (New) The electrochemical plating apparatus of claim 34, further comprising a valve in the fluid supply line, wherein the microprocessor-type controller is configured to close the valve in the fluid supply line and open the bleed line to drain a portion of the plating bath from the plating cell.

36. (New) The electrochemical plating apparatus of claim 28, wherein the microprocessor-type controller is configured to drain a portion of the plating bath from the plating cell during non-processing time periods by opening a selectively actuated bleed valve positioned in the bleed line.

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